

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.30594	100.0	4.4
			Subtotal	0.30594	100	4.4
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.02926	100.0	0.4208
	Pure metal	Aluminium (Al)	7429-90-5	0.17105	100.0	2.46
	Pure metal	Aluminium (Al)	7429-90-5	0.02926	100.0	0.4208
			Subtotal	0.22957	300	3.3016
Post-plating	Pure Metal	Tin (Sn)	7440-31-5	1.73828	100.0	25
			Subtotal	1.73828	100	25
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02336	0.04	0.336
	Copper alloy	Iron (Fe)	7439-89-6	0.05841	0.1	0.84
	Copper alloy	Copper (Cu)	7440-50-8	58.32451	99.86	838.824
			Subtotal	58.40628	100	840
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	3.40269	8.7	48.9375
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	6.25782	16.0	90
	Filler	Silica fused	60676-86-0	29.33351	75.0	421.875
	Carbon Black	Carbon black	1333-86-4	0.11733	0.3	1.6875
			Subtotal	39.11135	100	562.5
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.01043	5.0	0.15
	Lead alloy	Silver (Ag)	7440-22-4	0.00521	2.5	0.075
	Lead alloy	Lead (Pb)	7439-92-1	0.19295	92.5	2.775
			Subtotal	0.20859	100	3
			Total	100.00001	100	1438.2016

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